

Super FAP-G Series

N-CHANNEL SILICON POWER MOSFET

■ Features

- High speed switching
 - No secondary breakdown
 - Avalanche-proof
 - Low on-resistance
 - Low driving power

■ Applications

- Switching regulators
 - DC-DC converters
 - UPS (Uninterruptible Power Supply)

■ Maximum ratings and characteristicAbsolute maximum ratings

● (Tc=25°C unless otherwise specified)

Item	Symbol	Ratings	Unit	Remarks
Drain-source voltage	V _{DS}	450	V	
	V _{DSX}	450	V	V _{GS} =-30V
Continuous drain current	I _D	4.3	A	
Pulsed drain current	I _{D(puls)}	±17.2	A	
Gate-source voltage	V _{GS}	±30	V	
Repetitive or non-repetitive	I _{AR}	4.3	A	Note *1
Non-repetitive Maximum avalanche energy	E _{AS}	211	mJ	Note *2
Repetitive Maximum avalanche energy		2.1	mJ	Note *3
Maximum drain-source dV/dt	dV _{DS} /dt	20	kV/μs	V _{DS} ≤450V
Peak diode recovery dV/dt	dV/dt	5	kV/μs	Note *4
Max. power dissipation	P _D	2.16	W	T _A =25°C
		21	W	T _C =25°C
Operating and storage	T _{ch}	+150	°C	
temperature range	T _{stg}	-55 to +150	°C	
Isolation voltage	V _{ISO} *6	2	kVRms	t=60sec, f=60Hz

Note *1 Tch=150°C

Note *2 Starting Tch=25°C, IAS=1.8A, L=119mH, Vcc=45V, RG=50Ω

EAS limited by maximum channel temperature and avalanche current. See to 'Avalanche Energy' graph.

Note *3 Repetitive rating : Pulse width limited by maximum channel temperature.

Note *4. $|Z| = |D| \cdot di/dt = 50\Omega/\mu s$, $V_{OC} \leq RV_{DS(on)}$, $T_{ch} \leq 150^\circ C$

Note *4 $|I_{FSS} - I_D|$, $-di/dt = 50A/\mu s$, $V_{CC} \leq BV_{DSS}$, $T_{ch} \leq 150^\circ C$

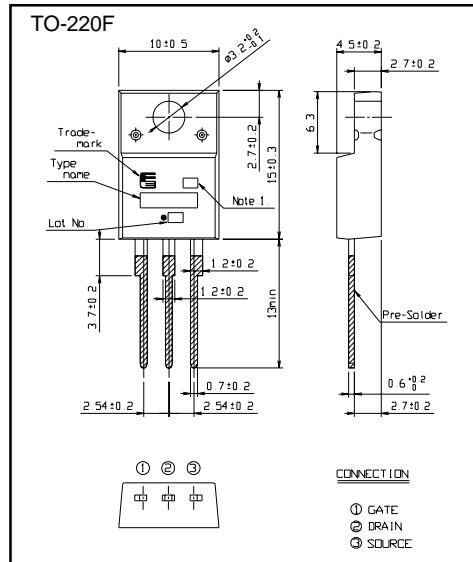
● Electrical characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Item	Symbol	Test Conditions					
Drain-source breakdown voltage	V(BR)DSS	Id= 250µA Vgs=0V		450		V	
Gate threshold voltage	Vgs(th)	Id= 250µA Vds=Vgs		3.0	5.0	V	
Zero gate voltage drain current	Idss	Vds=450V	Vgs=0V	Tch=25°C		25 µA	
		Vds=360V	Vgs=0V	Tch=125°C		2.0 mA	
Gate-source leakage current	IGSS	Vgs=±30V Vds=0V			100	nA	
Drain-source on-state resistance	RDS(on)	Id=2.1A Vgs=10V			1.30	1.60	Ω
Forward transconductance	gfs	Id=2.1A Vds=25V		1.8	3.5	S	
Input capacitance	Ciss	Vds=25V Vgs=0V f=1MHz			330	500	pF
Output capacitance	Coss				50	75	
Reverse transfer capacitance	Crss				2	4	
Turn-on time ton	td(on)	Vcc=300V Id=2.1A Vgs=10V Rgs=10Ω			11	17.5	ns
	tr				5.5	8.5	
Turn-off time toff	td(off)				23	34.5	
	tf				5.0	8.0	
Total Gate Charge	QG	Vcc=225V Id=4.3A Vgs=10V			13.0	20	nC
Gate-Source Charge	QGS				6.0	9.0	
Gate-Drain Charge	QGD				2.5	3.8	
Diode forward on-voltage	VSD	If=4.3A Vgs=0V Tch=25°C			1.00	1.50	V
Reverse recovery time	trr	If=4.3A Vgs=0V -di/dt=100A/µs Tch=25°C			280		ns
Reverse recovery charge	Qrr				1.6		µC

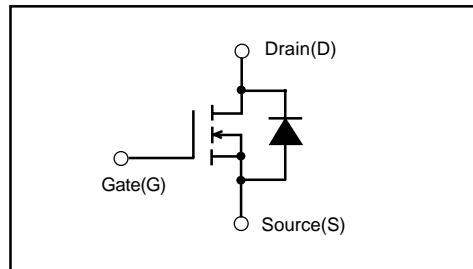
● Thermal characteristics

Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal resistance	R _{th(ch-c)}	channel to case			5.952	°C/W
	R _{th(ch-a)}	channel to ambient			58.0	°C/W

■ Outline Drawings [mm]



■ Equivalent circuit schematic



■ Characteristics

